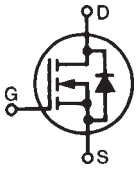
IXYS

X3-Class HiPerFET™ Power MOSFET

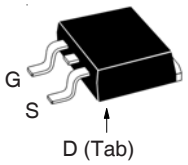
IXFA90N20X3

V_{DSS} = 200V
I_{D25} = 90A
$R_{DS(on)}$ ≤ 12.8mΩ

N-Channel Enhancement Mode
Avalanche Rated



TO-263



G = Gate D = Drain
S = Source Tab = Drain

Symbol	Test Conditions	Maximum Ratings	
V_{DSS}	T_J = 25°C to 150°C	200	V
V_{DGR}	T_J = 25°C to 150°C, R_{GS} = 1MΩ	200	V
V_{GSS}	Continuous	±20	V
V_{GSM}	Transient	±30	V
I_{D25}	T_C = 25°C	90	A
I_{DM}	T_C = 25°C, Pulse Width Limited by T_{JM}	220	A
I_A	T_C = 25°C	45	A
E_{AS}	T_C = 25°C	1.5	J
dv/dt	$I_S \le I_{DM}$, $V_{DD} \le V_{DSS}$, $T_J \le 150°C$	20	V/ns
P_D	T_C = 25°C	390	W
T_J		-55 ... +150	°C
T_{JM}		150	°C
T_{stg}		-55 ... +150	°C
T_L	Maximum Lead Temperature for Soldering	300	°C
dT/dt	Heating / Cooling rate, 175°C - 210°C	50	°C/min
T_{SOLD}	1.6 mm (0.062in.) from Case for 10s	260	°C
F_C	Mounting Force	10..65 / 2.2..14.6	N/lb
Weight		2.5	g

Symbol	Test Conditions (T_J = 25°C, Unless Otherwise Specified)	Characteristic Values Min.	Typ.	Max.	
BV_{DSS}	V_{GS} = 0V, I_D = 250μA	200			V
$V_{GS(th)}$	$V_{DS} = V_{GS}$, I_D = 1.5mA	2.5		4.5	V
I_{GSS}	V_{GS} = ±20V, V_{DS} = 0V			±100	nA
I_{DSS}	$V_{DS} = V_{DSS}$, V_{GS} = 0V			5	μA
	T_J = 125°C			300	μA
$R_{DS(on)}$	V_{GS} = 10V, $I_D = 0.5 \bullet I_{D25}$, Note 1			12.8	mΩ

Features

- International Standard Package
- Low $R_{DS(ON)}$ and Q_G
- Avalanche Rated
- Low Package Inductance

Advantages

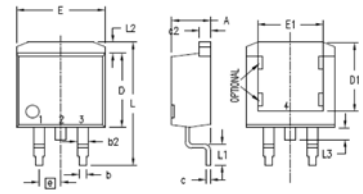
- High Power Density
- Easy to Mount
- Space Savings

Applications

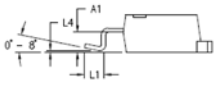
- Switch-Mode and Resonant-Mode Power Supplies
- DC-DC Converters
- PFC Circuits
- AC and DC Motor Drives
- Robotics and Servo Controls

Symbol	Test Conditions (T_J = 25°C, Unless Otherwise Specified)	Characteristic Values Min.	Typ.	Max	
g_{fs}	V_{DS} = 10V, I_D = 0.5 • I_{D25}, Note 1	40	67		S
R_{Gi}	Gate Input Resistance		1.4		Ω
C_{iss}	V_{GS} = 0V, V_{DS} = 25V, f = 1MHz		5420		pF
C_{oss}			930		pF
C_{rss}			4		pF
	Effective Output Capacitance				
$C_{o(er)}$	Energy related: V_{GS} = 0V, V_{DS} = 0.8 • V_{DSS}		420		pF
$C_{o(tr)}$	Time related: V_{GS} = 0V, V_{DS} = 0.8 • V_{DSS}		1300		pF
$t_{d(on)}$	**Resistive Switching Times**		22		ns
t_r	V_{GS} = 10V, V_{DS} = 0.5 • V_{DSS}, I_D = 0.5 • I_{D25}		26		ns
$t_{d(off)}$	R_G = 5Ω (External)		62		ns
t_f			13		ns
$Q_{g(on)}$	V_{GS} = 10V, V_{DS} = 0.5 • V_{DSS}, I_D = 0.5 • I_{D25}		78		nC
Q_{gs}			23		nC
Q_{gd}			22		nC
R_{thJC}				0.32	°C/W

TO-263 (IXFA) Outline



1 = Gate
2 = Drain
3 = Source
4 = Drain



SYM	INCHES MIN	INCHES MAX	MILLIMETERS MIN	MILLIMETERS MAX
A	.160	.190	4.06	4.83
A1	.080	.110	2.03	2.79
b	.020	.039	0.51	0.99
b2	.045	.055	1.14	1.40
c	.016	.029	0.40	0.74
c2	.045	.055	1.14	1.40
D	.340	.380	8.64	9.65
D1	.315	.350	8.00	8.89
E	.380	.410	9.65	10.41
E1	.245	.320	6.22	8.13
e	.100 BSC		2.54 BSC	
L	.575	.625	14.61	15.88
L1	.090	.110	2.29	2.79
L2	.040	.055	1.02	1.40
L3	.050	.070	1.27	1.78
L4	0	.005	0	0.13

Source-Drain Diode

Symbol	Test Conditions (T_J = 25°C, Unless Otherwise Specified)	Characteristic Values Min.	Typ.	Max	
I_S	V_{GS} = 0V			90	A
I_{SM}	Repetitive, pulse Width Limited by T_{JM}			360	A
V_{SD}	I_F = I_S, V_{GS} = 0V, Note 1			1.4	V
t_{rr}	I_F = 45A, -di/dt = 100A/μs		95		ns
Q_{RM}	V_R = 100V		360		nC
I_{RM}			7.6		A

Note 1. Pulse test, t ≤ 300μs, duty cycle, d ≤ 2%.

Fig. 1. Output Characteristics @ T_J = 25°C

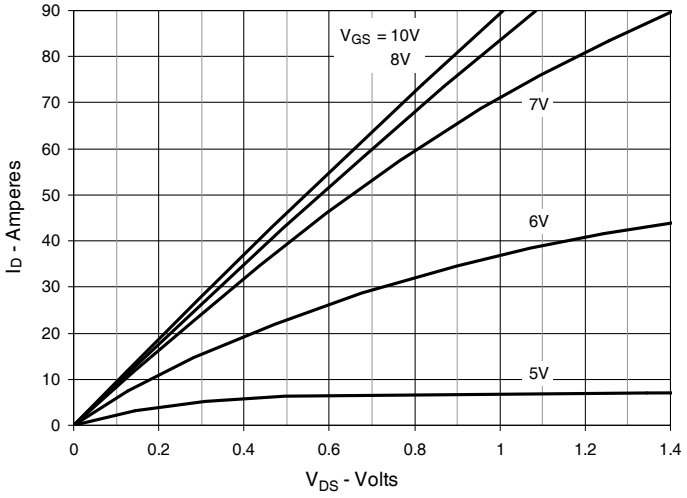


Fig. 2. Extended Output Characteristics @ T_J = 25°C

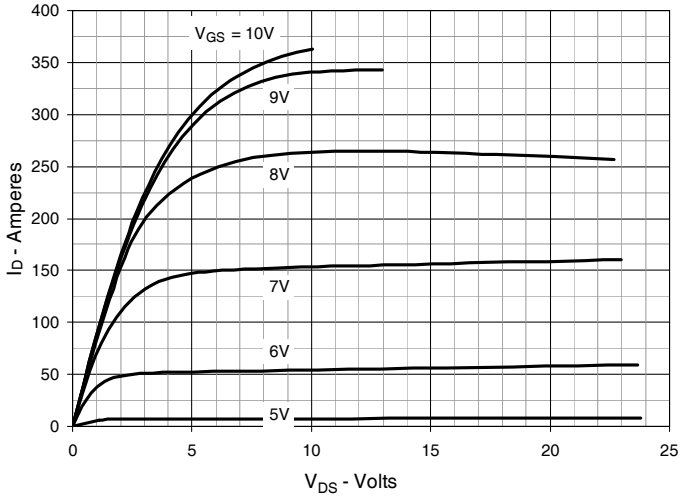


Fig. 3. Output Characteristics @ T_J = 125°C

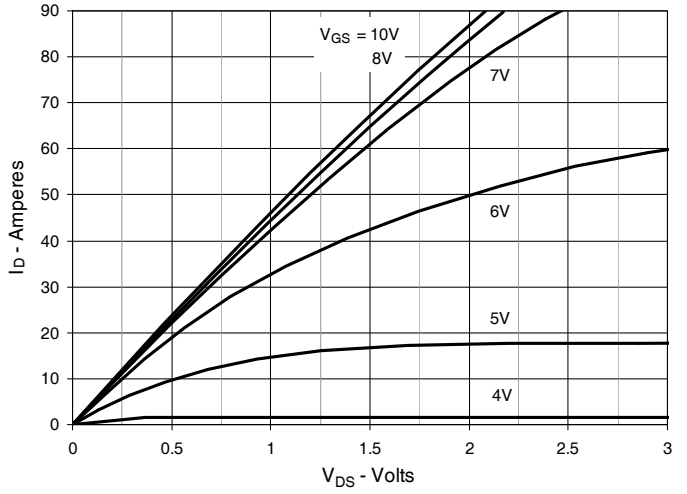


Fig. 4. $R_{DS(on)}$ Normalized to I_D = 45A Value vs. Junction Temperature

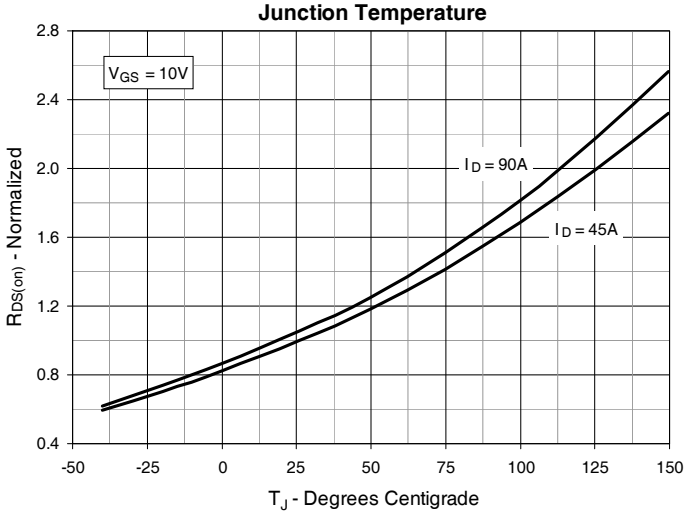


Fig. 5. $R_{DS(on)}$ Normalized to I_D = 45A Value vs. Drain Current

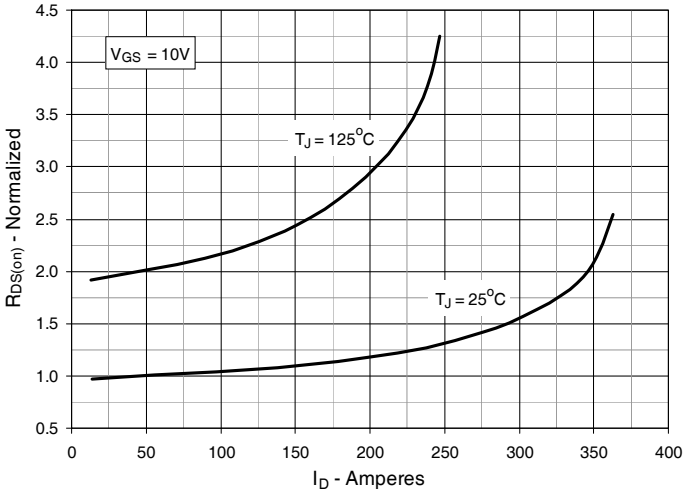


Fig. 6. Normalized Breakdown & Threshold Voltages vs. Junction Temperature

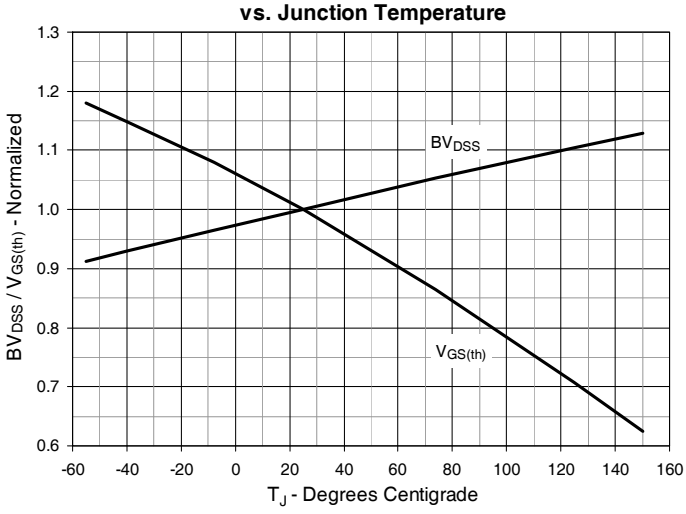


Fig. 7. Maximum Drain Current vs. Case Temperature

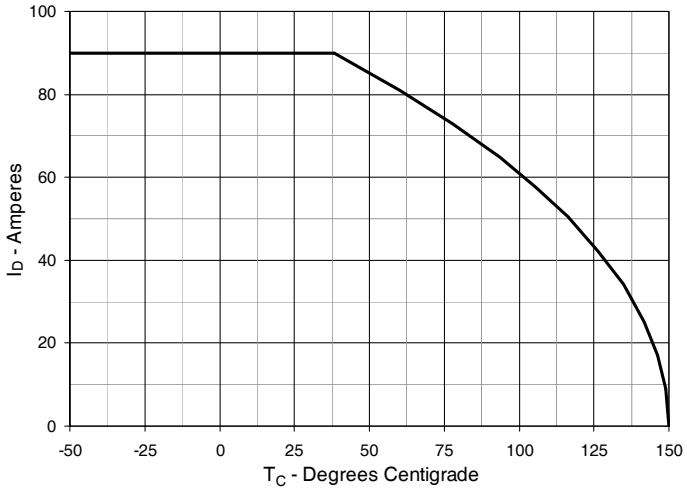


Fig. 8. Input Admittance

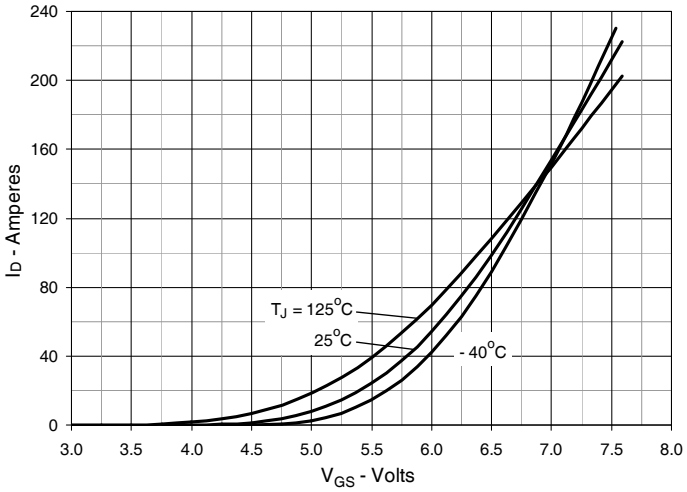


Fig. 9. Transconductance

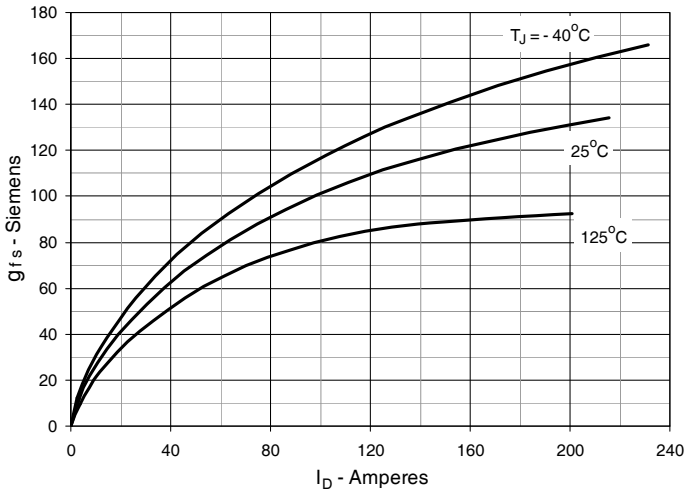


Fig. 10. Forward Voltage Drop of Intrinsic Diode

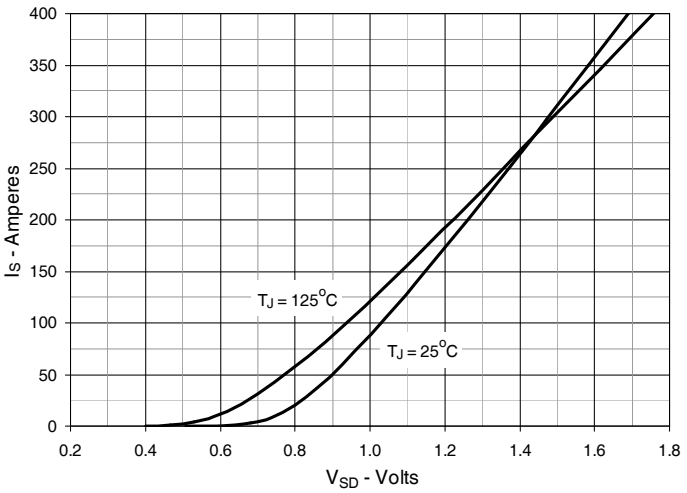


Fig. 11. Gate Charge

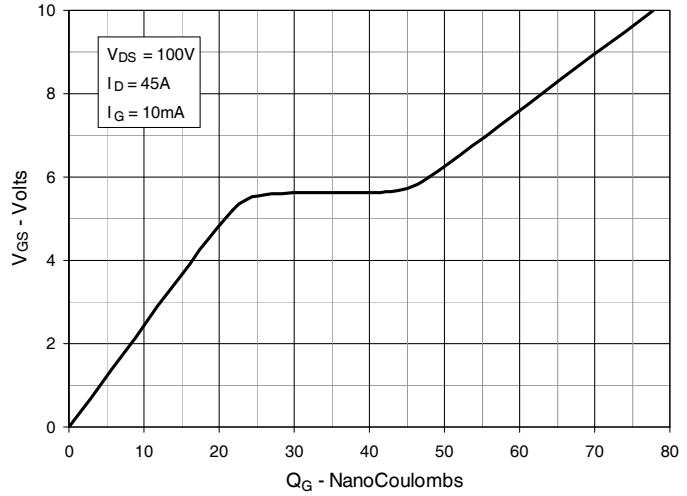


Fig. 12. Capacitance

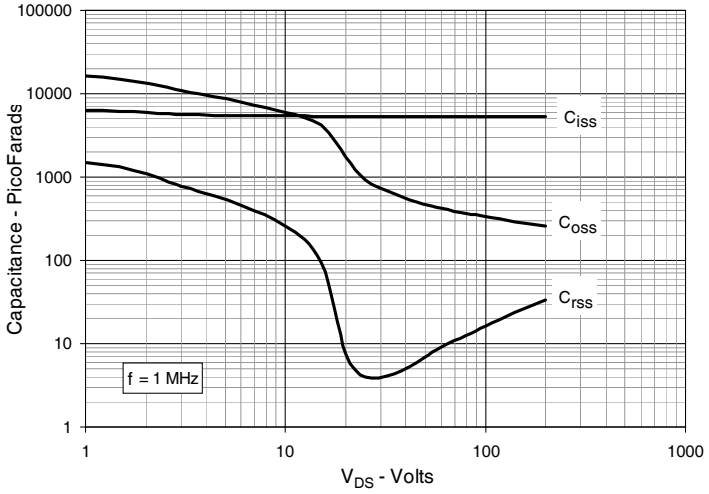


Fig. 13. Output Capacitance Stored Energy

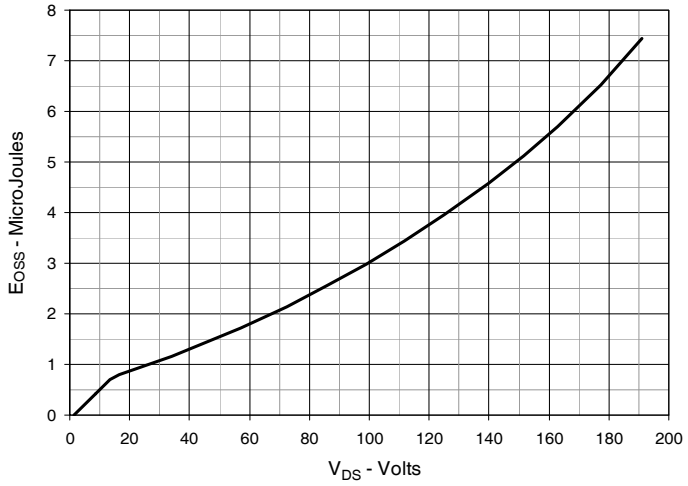


Fig. 14. Forward-Bias Safe Operating Area

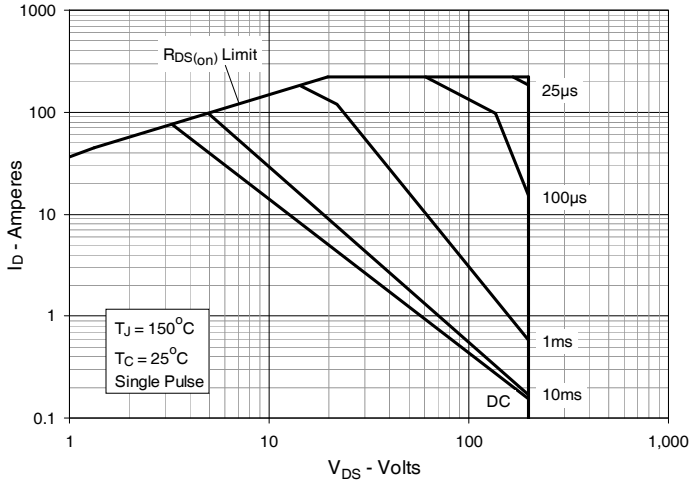


Fig. 15. Maximum Transient Thermal Impedance